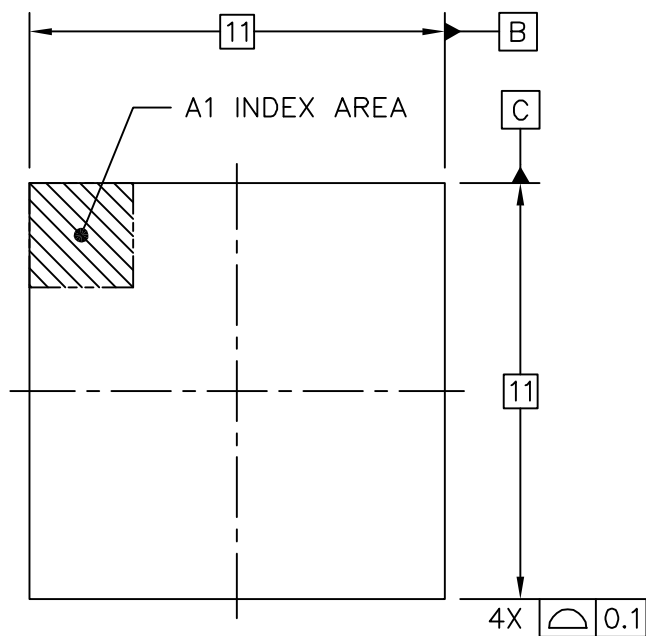
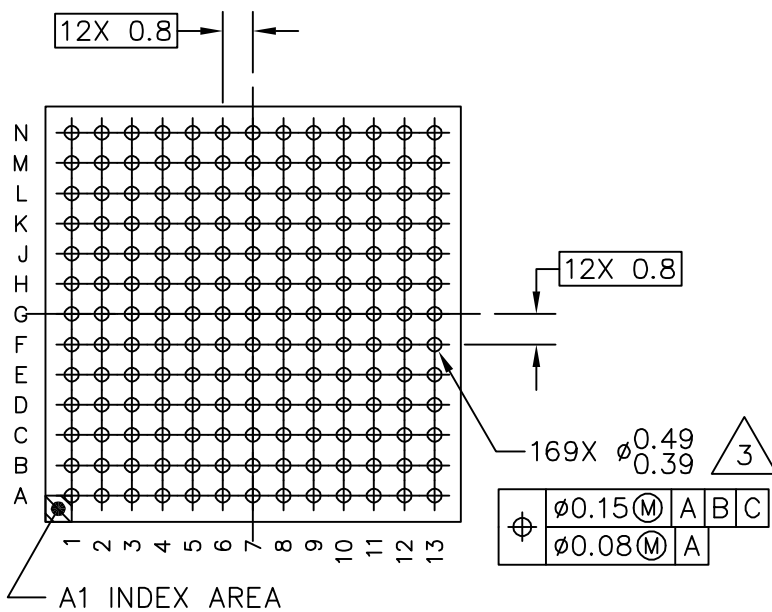
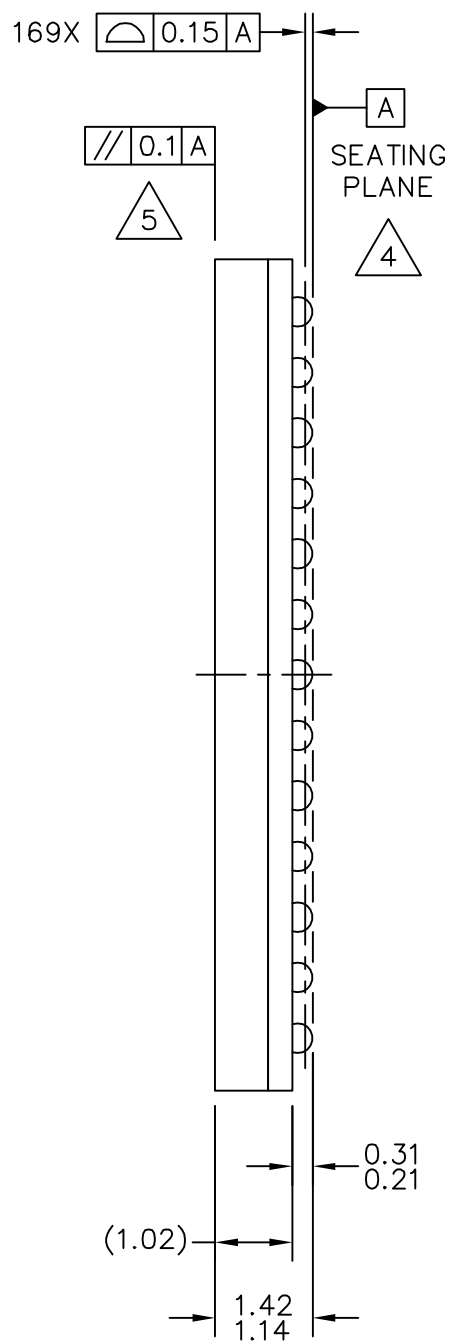




TOP VIEW



BOTTOM VIEW



SIDE VIEW

© FREESCALE SEMICONDUCTOR, INC.
ALL RIGHTS RESERVED.

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: PBGA, LOW PROFILE,
FINE PITCH, 169 I/O,
11 X 11 PKG, 0.8 MM PITCH (MAP)

DOCUMENT NO: 98ARE10745D

REV: A

CASE NUMBER: 2035-01

05 JUN 2008

STANDARD: NON-JEDEC

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE: PBGA, LOW PROFILE, FINE PITCH, 169 I/O, 11 X 11 PKG, 0.8 MM PITCH (MAP)			DOCUMENT NO: 98ARE10745D		REV: A
			CASE NUMBER: 2035–01		05 JUN 2008
			STANDARD: NON–JEDEC		